



TG-CJ-Li-60-60-15-PF Ceramic Heatsink

Version 3.220318

Ceramic Heatsink

T-Global's range of ceramic heatsinks have been designed from a proprietary blend of engineering ceramics to offer superior thermal management for the most demanding of applications. Compared to aluminium, ceramics confer additional benefits such as electrically isolating, resistant to corrosion, low weight and does not act like an antenna. The addition of a pre-applied thermal tape further reduces the manufacturing complexity when compared to aluminium heatsinks.

Features

- Large contact area
- Low weight
- High breakdown voltage
- Excellent heat spreader
- Custom shapes possible

Applications

LED, M/B, P/S, LCD, TV, Notebook, PC, PC Telecom Device, Wireless Hub, Power transistor, Power module, CPU, Chip IC

Properties

- ✓ REACH Compliant
- ✓ ROHS Compliant

Main Component		Technical Ceramic	
Property Type	Property	Unit	
Physical Property	Density	g/cm ³	3.66
	Water Absorption	%	0.002
	Sinter Temperature	°C	1700
	Acid Resistance	mg/cm ³	≤0.2
	Alkali	mg/cm ³	≤0.2
Mechanical Property	Mohs Hardness	HV	9
	Bend Strength	Mpa	≥ 610
	Compression Intensity	Mpa	≥ 620
Thermal Property	Maximum Working Temperature	°C	1400
	Thermal Expansion Coefficient	(1×10 ⁻⁶) mm/°C	7.8-8.3
	Thermal Shock Resistance	T (°C)	200
	Thermal Conductivity	W/m.k.	40-51
Electrical Property	Resisting Rate of Volume	Ω °C	1016
	DC Breakdown Strength	KV/mm	15.2-16.7
	Insulation Breakdown Intensity	KV/mm	18
	Dielectric Constant (1MHz)	(E)	10
	Dielectric Dissipation	(tg o)	0.4*10 ⁻³
Shelf Life of Tape	(can be requalified for further 12)	months	12

Part Number Information

Product	Length	Width	Depth	Adhesive
TG-CJ-Li-60-60-15-PF	60	60	15	1 Sided Tape

* All measurements in mm

T-Global Technology Limited
1 & 2 Cosford Business Park, Central Park,
Lutterworth, Leicestershire LE17 4QU U.K.

Tel: +44 (0)1455 553 510
Email: sales@tglobaltechnology.com
Web: www.tglobaltechnology.com
Skype: tglobal.technology
VAT #: GB 116 662 714

NOTICE: The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own test to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated in T-Global Technology Europe and North America's invoice, quotation, or order acknowledgment. We disclaim any and all liabilities incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any process or to manufacture or to use any product in conflict with existing or future patents covering any product or material or its use.



TG-CJ-Li-60-60-15-PF Ceramic Heatsink

* Data for design engineer guidance only. Observed performance varies in application. Engineers are reminded to test the material in application.

NOTICE: The information contained herein is to the best of our knowledge true and accurate. However, since the varied conditions of potential use are beyond our control, all recommendations or suggestions are presented without guarantee or responsibility on our part and users should make their own test to determine the suitability of our products in any specific situation. This product is sold without warranty either expressed or implied, of fitness for a particular purpose or otherwise, except that this product shall be of standard quality, and except to the extent otherwise stated T-Global Technology Europe and North America's invoice, quotation, or order acknowledgment. We disclaim any and liability incurred in connection with the use of information contained herein, or otherwise. All risks of such are assumed by the user. Furthermore, nothing contained herein shall be construed as a recommendation to use any process or to manufacture or to use any product in conflict with existing future patents covering any product or material or its use.